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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/727,662	12/05/2003	Jiro Matsumoto	F00ED0150-DIV	4972
26071	7590	06/29/2005	EXAMINER	
JUNICHI MIMURA OKI AMERICA INC. 1101 14TH STREET, N.W. SUITE 555 WASHINGTON, DC 20005			PERALTA, GINETTE	
			ART UNIT	PAPER NUMBER
			2814	

DATE MAILED: 06/29/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Office Action Summary</b>	Application No. 10/727,662	Applicant(s) MATSUMOTO, JIRO	
	Examiner Ginette Peralta	Art Unit 2814	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

### Status

- 1) ☐ Responsive to communication(s) filed on \_\_\_\_.
- 2a) ☐ This action is **FINAL**.                      2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

### Disposition of Claims

- 4) ☒ Claim(s) 1-56 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1-56 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_ are subject to restriction and/or election requirement.

### Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

### Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All    b) ☐ Some \* c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
  2. ☒ Certified copies of the priority documents have been received in Application No. 10/103,889.
  3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

### Attachment(s)

- |  |  |
|--|--|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)  | 4) <input type="checkbox"/> Interview Summary (PTO-413)<br>Paper No(s)/Mail Date. ____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)   | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)            |
| 3) <input checked="" type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)<br>Paper No(s)/Mail Date <u>12/5/03</u> . | 6) <input type="checkbox"/> Other: ____  |

## DETAILED ACTION

### *Claim Rejections - 35 USC § 112*

1. The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

2. Claims 43-44 are rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the enablement requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to enable one skilled in the art to which it pertains, or with which it is most nearly connected, to make and/or use the invention.

Claim 43 recites "a gate of a sealing device having a mold in which a semiconductor wafer having semiconductor elements on its surface is set in order to form a resin layer on the semiconductor wafer by introducing a melted resin from a resin supplier, the gate introducing the melted resin into the mold from a part of a periphery of the semiconductor wafer, and a depth of the gate is lower than the thickness of the resin layer", it is unclear the location of the gate, and what is intended to be described with the phrase "a depth of the gate is lower than the thickness of the resin layer", there is no support in the specification for this limitation nor the feature is described in such a way as to enable one skilled in the art to use or form a gate like the one described, thus claims 43 and 44 are not enabled by the specification.

*Claim Rejections - 35 USC § 102*

3. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

4. Claims 1, 6-28, 32, 37-42, and 45-56 are rejected under 35 U.S.C. 102(b) as being anticipated by Miyajima (JP 2000-299335).

Regarding claim 1, Miyajima discloses in Figs. 14-17 a sealing apparatus for sealing a semiconductor wafer 90 having semiconductor elements on its surface by resin 50, comprising an upper mold 20; and a lower mold 21 having an area where the semiconductor wafer is mounted, the lower mold having an uneven surface in the area, as shown in Figs. 1, 16 and 17.

Regarding claim 6, Miyajima discloses in Fig. 17 that slits 98, 76a, 98a, and 77 form the uneven surface.

Regarding claim 7, Miyajima discloses in Fig. 17 that the slits 76a are formed in parallel to each other.

Regarding claims 8 and 9, Miyajima discloses in Figs. 16 and 17 that in the sealing apparatus the area is a first area 21, the slits are formed within a second area, which is in the first area, and the slits are not extended to the periphery of the first area.

Regarding claim 10, Miyajima discloses that the uneven surface is formed by a single spiral slit 98, as shown in Figs. 16 and 17.

Regarding claim 11, Miyajima discloses in Fig. 17 that the area is a first area, the single spiral slit 98 is formed within a second area, which is in the first area, and the single spiral slit 98 is not extended to the periphery of the first area.

Regarding claims 12, and 13, Miyajima discloses in Fig. 14 a sealing apparatus further comprising a shock absorbers 78, which are formed under the lower mold 21, buffering stress from the upper mold 20 when the semiconductor wafer is sandwiched by the upper and lower molds, the shock absorbers being disposed symmetrically against the center of the area.

Regarding claims 14 and 15, Miyajima discloses that the shock absorber 78 is formed by a metallic compression spring.

Regarding claims 16, 17, 20, and 21, Miyajima discloses in Figs. 14 and 19, that the shock absorber 78 is a first shock absorber 78, and further comprising a first block 74 having a first recess, the lower mold 21 being contained in the first recess; a second block 76 having a second recess, the first block 74 being contained in the second recess; and second shock absorbers, as shown in Fig. 19, which are formed under the second block, buffering stress from the upper mold when the semiconductor wafer is sandwiched by the upper and the lower mold.

Regarding claims 18, 19, 22, and 23, Miyajima discloses that the second shock absorbers are formed by a metallic compression spring as shown in Fig. 19.

Regarding claim 24, Miyajima discloses in Figs. 14-17 a sealing apparatus for sealing a semiconductor wafer 90 having semiconductor elements on its surface by resin 50, comprising an upper mold 20; and a lower mold 21 having an area where the semiconductor wafer is mounted, the lower mold having an uneven surface in the area, as shown in Figs. 1, 16 and 17; and the upper mold 20 including a cavity 96, 98, 20c on the main surface, and wherein the semiconductor wafer is sandwiched at its periphery by the main surface of the upper mold 20 other than an area where the cavity is formed and the lower mold whereby the resin is not formed on the periphery of the semiconductor wafer.

Regarding claim 25, Miyajima discloses that the cavity is located at a position corresponding to the area, wherein the upper mold further includes a gate, as shown in Fig. 12, connected to the cavity and cull 68 connected to the gate, wherein the gate is located at a position corresponding the periphery of the semiconductor wafer, and where the cavity is formed deeper than the gate.

Regarding claim 26, Miyajima discloses in Fig. 12 that the width of the gate is expanding toward the cavity.

Regarding claims 27 and 28, Miyajima discloses in Figs. 10-15 that the upper mold includes an air vent 96, which is located at a position opposite to the gate, for releasing air in the cavity when the semiconductor wafer is sealed.

Regarding claim 32, Miyajima discloses in Figs. 14-17 a semiconductor device manufacturing mold for setting a semiconductor wafer 90 having semiconductor

elements on its surface by resin 50, comprising an upper mold 20; and a lower mold 21 having an area where the semiconductor wafer is mounted, the lower mold having an uneven surface in the area, as shown in Figs. 1, 16 and 17.

Regarding claim 37, Miyajima discloses in Figs. 16 and 17 that the uneven surface is formed by slits 96, 98, 76a, 98a, and 77.

Regarding claim 38, Miyajima discloses in Fig. 16 and 17 that the slits 96 and 76a are formed in parallel to each other.

Regarding claims 39 and 40, Miyajima discloses in Fig. 17 that in the sealing apparatus the area is a first area 21, the slits are formed within a second area, which is in the first area, and the slits are not extended to the periphery of the first area.

Regarding claim 41, Miyajima discloses that the uneven surface is formed by a single spiral slit 98, as shown in Figs. 16 and 17.

Regarding claim 42, Miyajima discloses in Figs. 16 and 17 that the area is a first area, the single spiral slit 98 is formed within a second area, which is in the first area, and the single spiral slit 98 is not extended to the periphery of the first area.

Regarding claims 45 and 46, Miyajima discloses in Figs. 14-17 in Figs. 14-17 a sealing apparatus for sealing a semiconductor wafer 90 having semiconductor elements on its surface by resin 50, comprising an upper mold 20; and a lower mold 21 having an area where the semiconductor wafer is mounted, and shock absorbers 78, which are formed under the lower mold 21, buffering stress from the upper mold 20

when the semiconductor wafer is sandwiched by the upper and lower molds, the shock absorbers being disposed symmetrically against the center of the area.

Regarding claims 47 and 48, Miyajima discloses that the shock absorber 78 is formed by a metallic compression spring.

Regarding claims 49, 50, 53, and 54, Miyajima discloses in Figs. 14 and 19, that the shock absorber 78 is a first shock absorber 78, and further comprising a first block 74 having a first recess, the lower mold 21 being contained in the first recess; a second block 76 having a second recess, the first block 74 being contained in the second recess; and second shock absorbers, as shown in Fig. 19, which are formed under the second block, buffering stress from the upper mold when the semiconductor wafer is sandwiched by the upper and the lower mold.

Regarding claims 51, 52, 55, and 56, Miyajima discloses that the second shock absorbers are formed by a metallic compression spring as shown in Fig. 19.

*Claim Rejections - 35 USC § 103*

5. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

6. Claims 29-31 are rejected under 35 U.S.C. 103(a) as being unpatentable over Miyajima in view of Yamamoto (U. S. Pat. 6,630,374 B2).

Miyajima discloses in Figs. 14-17 a sealing apparatus for sealing a semiconductor wafer 90 having semiconductor elements on its surface by resin 50, comprising an upper mold 20; and a lower mold 21 having an area where the semiconductor wafer is mounted, the lower mold having an uneven surface in the area, as shown in Figs. 1, 16 and 17; and the upper mold 20 including a cavity 96, 98, 20c on the main surface, and wherein the semiconductor wafer is sandwiched at its periphery by the main surface of the upper mold 20 other than an area where the cavity is formed and the lower mold whereby the resin is not formed on the periphery of the semiconductor wafer.

Miyajima discloses the claimed invention with the exception of a projection member being formed underneath the center of a back surface the lower mold, which is opposite to the uneven surface, ejection pins formed in the lower mold; the ejection pins pushing the semiconductor wafer up after the semiconductor wafer is sealed by the resin; and the ejection pins disposed symmetrically against the center of the area.

Yamamoto discloses in Figs. 1A, 2A, 2C, among others, a sealing apparatus for sealing a semiconductor wafer by resin that comprises an upper mold 1; and a lower mold 2; wherein the structure further comprises a projection member 5 being formed underneath the center of a back surface of the lower mold 2, which is opposite to a top surface where the semiconductor wafer is located; ejection pins 10 formed in the lower mold, the ejection pins pushing the semiconductor wafer up after the semiconductor wafer is sealed by the resin; and the ejection pins being disposed symmetrically against

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the center of the area, wherein the projection and the ejection pins are taught for the disclosed intended purpose of providing means for effectively applying resin and removing the completed resin sealed semiconductor wafer from the lower mold.

*Allowable Subject Matter*

7. Claims 2-5, and 33- 36 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

The primary reason for the allowance of the claims is the inclusion of the feature of a sealing apparatus for sealing a semiconductor wafer by resin that comprises an upper mold; and a lower mold having an area where the semiconductor wafer is mounted, the lower mold having an uneven surface area formed by an electric discharging process in coarse condition which is not anticipated nor rendered obvious over the prior art of record. The prior art of record discloses that the uneven surface is formed by openings and not by an uneven surface formed by an electric discharging process in coarse conditions, which would result in a roughened surface, not a surface with openings.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Ginette Peralta whose telephone number is (571) 272-1713. The examiner can normally be reached on Monday to Friday 8:00 AM- 5:30 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (571) 272-1705. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

GP

A handwritten signature in black ink, appearing to read 'Hoai Pham', with a long horizontal flourish extending to the right.

HOAI PHAM  
PRIMARY EXAMINER